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Welcome to the tenth newsletter of the **2007 iNEMI Roadmap** cycle. This and subsequent newsletters will be completely dedicated to keeping you informed about the progress of the **2007 iNEMI Roadmap**. Please pass this newsletter on to anyone within your technical network who might be interested in becoming involved in this effort.

2007 iNEMI Roadmap North American Workshop

The International Electronics Manufacturing Initiative (iNEMI) will hold a workshop for its 2007 Roadmap on Wednesday, May 17, at consortium headquarters in Herndon, Virginia. The workshop is a full-day meeting, scheduled from 8:00 a.m. to 5:30 p.m., and is open to non-members.

This workshop provides a progress report on the roadmap, and gives industry an advance look at key findings. It also provides the opportunity for industry feedback — kind of a “reality check” on the conclusions being drawn — and allows mid-course corrections, if necessary. Participants have the advantage of gaining early insight into the anticipated future direction of the electronics industry, and discussions and feedback help us improve the final roadmap report.

The workshop plans to include presentations from all 19 Technology Working Groups (TWGs).

The North American workshop is one of several regional meetings scheduled for the **2007 iNEMI Roadmap**. There was also a workshop held in Europe on April 5, co-located with SEMICON Europa (Munich), and one scheduled in China on June 27, in conjunction with HDP '06 in Shanghai (*see item below*).

The North American workshop registration fee is \$200 for non-members, which includes a continental breakfast, lunch, access to workshop presentations and a copy of the 2007 iNEMI Roadmap CD when published in February 2007 (which sells for \$250). There is no fee for presenters and certain invited industry experts. **TWG Chair presenters need to register as members** and, as usual, TWG Chairs will receive a final copy of their chapters from the **2007 iNEMI Roadmap**.

Presentations from the workshop will be placed on the iNEMI FTP site for downloading following the meeting and access information will be provided at the workshop. Registration deadline is May 12 (earlier if the meeting reaches capacity). For hotels in the area, please go to: http://www.inemi.org/cms/contact/contact_hotels.html

For additional information about, or to register for, the North American workshop, go to http://www.inemi.org/cms/calendar/iNEMI_Roadmap_North_American_workshop.html

2007 iNEMI Roadmap - North American Workshop
Preliminary Agenda
May 17, 2006
Herndon, VA

Time	Subject	Presenter
7:30 a.m.	Continental Breakfast	
7:50 a.m.	Welcome/Overview Presentation	Jim McElroy, iNEMI, Chuck Richardson, iNEMI
8:20 – 4:20	Technology Working Group Reports: (20 minutes each)	
	Business Processes / Technologies:	
8:20 a.m.	Product Lifecycle Information Management	Eric Simmon, NIST
	Design Technologies:	
8:40 a.m.	Modeling, Simulation & Design Tools	S.B. Park, Binghamton U.
9:00 a.m.	Thermal Management	Carl Fisher, 3M
9:20 a.m.	Environmentally Conscious Electronics	Mark Newton, Dell
9:40 – 10:10	Discussion / Break	
	Manufacturing Technologies:	
10:10 a.m.	Board assembly	David Geiger, Flextronics
10:30 a.m.	Test, Inspection & Measurement	Michael Reagin, Delphi
10:50 a.m.	Final Assembly	Steve Davidson, Delphi
	Component Subsystem Technologies:	
11:10 a.m.	Packaging	Joe Adam, Skyworks
11:30 a.m.	RF Components & Subsystems	Steve Kenney, Georgia Tech
11:50 a.m.	Organic Substrates	Jack Fisher, IPC/iNEMI
12:10 p.m.	Optoelectronics	Rick Clayton, Consultant
12:30 – 1:30	Lunch / Discussion	
1:30 p.m.	Mass Data Storage	Tom Coughlin, Consultant
1:50 p.m.	Connectors	John MacWilliams, Consultant
2:10 p.m.	Energy Storage Systems	Ralph Brodd, Broddarp
2:30 p.m.	Interconnect Substrates – Ceramic	Howard Imhof, Metalor
2:50 – 3:20	Discussion / Break	

3:20 p.m.	Passive Components	Joe Dougherty, Penn State
3:40 p.m.	Sensors	Tim McBride, TI
4:00 p.m.	Semiconductor Technology	Alan Allan, Intel
4:20 p.m.	Organic & Printed Electronics	Dan Gamota, Motorola
5:00 p.m.	Summary	Chuck Richardson, iNEMI Bob Pfahl, iNEMI
5:30 p.m.	Close	

2007 iNEMI Roadmap - Asian Workshop June 27, 2006

The roadmap workshop in Asia is being held in conjunction with HDP '06 and will be held at the Yan Chang Campus of Shanghai University (Shanghai). The workshop will feature presentations on key roadmap areas thought to be of particular interest in Asia. Watch the [iNEMI website](#) for a detailed agenda. Registration is being handled through HDP'06 and a registration form can be downloaded from the [HDP website](#) at <http://www.hdp-shanghai.com/>

Recent Activity

PEG Update. PEGs are working toward completing their chapter / emulator drafts for use by the TWGs in getting ready for the North American Workshop on May 17 and the Asian Workshop on June 27th. The 2007 version of the Consumer / Portable and Aerospace / Defense emulator spreadsheets have been distributed to TWG Chairs and the Office / Large Business / Communications emulator is promised by June 15. Promise dates for the remaining PEGs will be forthcoming.

TWG Update. All the TWG committees are busily working toward completing their status presentations for the May 17 North American Workshop in Herndon, Virginia.

We are offering the TWG Chairs meeting rooms before and after the May 17 workshop so that you can take advantage of the face-to-face time for working on your TWG chapters while in Herndon. Please let me know of any room needs as soon as possible.

We are pleased to announce that **Rick Clayton of Clayton & Associates** has agreed to chair the **Optoelectronics TWG**. He will be contacting everyone who previously served on the OE TWG to schedule a TWG meeting. During this roadmap we will be working to strengthen our relationship with OIDA on the roadmap process. If you have questions, please contact Rick at rick@clayton-assoc.com.

We are also pleased to announce that **Randy Malik, IBM**, has agreed to co-chair the **Energy Storage and Conversion Systems TWG**. He will bring his expertise in the power conversion area to help address the need for increased energy efficiency in power supplies.

Roadmap Overview

To access a short overview of the roadmap process – including a list of the 2007 iNEMI Roadmap chapters, please follow this link:

http://www.inemi.org/cms/roadmapping/About_RM_Newsletter.html

Get Involved

The iNEMI roadmap has become recognized as an important tool for defining the “state of the art” in the electronics industry as well as identifying emerging and disruptive technologies. It also fuels development of future iNEMI projects and sets priorities for industry R&D over the next 10 years. With the “globalization” of the iNEMI roadmap, the next “edition” should become even more important as a tool for identifying technology gaps and possible solutions for an increasingly global industry.

If you would like to be involved with the *2007 iNEMI Roadmap* team, or be added to the mailing list of this monthly newsletter, please contact Chuck Richardson at Chuck.Richardson@inemi.org.

For more detailed information about the meetings discussed above, please contact Linda Anderson-Jessup at +1 703-834-2086 or linda.jessup@inemi.org.

From the Editor: We hope that you will find this newsletter interesting and informative. If you would like to access an issue of a past roadmap newsletter or check other roadmap information, please use the iNEMI website link: <http://www.inemi.org/roadmapping/status.html>.

Please provide comments to Chuck Richardson at 1-256-880-0922 or email Chuck.Richardson@inemi.org.

2007 iNEMI Roadmap Calendar

May 8, 2006	Teleconference with TWG Chairs
May 17, 2006	Roadmap Workshop, Herndon, VA
May 18, 2006	TC Meeting in Herndon (Roadmap)
June 27, 2006	Roadmap Workshop at HDP '06, Shanghai, China
July 1, 2006	TWG Drafts Due for TC Review
August 9, 10, 2006	TC Face-to-Face Review with TWG Chairs in Kokomo
September 2006	Council Review of Key Issues and Preliminary Summary @ SMTAI, Final Roadmap Chapters Due 9/22/06
October 31, 2006	Edit, Prepare Appendix A-D, Executive Summary
November 20, 2006	Go To “Press”
December 4, 2006	Ship to Members
February 2007	Industry Release at APEX